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Production Custom designs Installation



SPECIFICATION FOR LCM Module

MODULE No:	ET027HV21-K
CUSTOMER:	

YOURITECH	INITIAL	DATE
PREPARED BY		
CHECKED BY		
APPROVED BY		

CUSTOMER	INITIAL	DATE
APPROVED BY		



[illegible]

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* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This module is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 2.73 " TFT-LCD contains 320x320 pixels, and can display up to 16.7M colors.

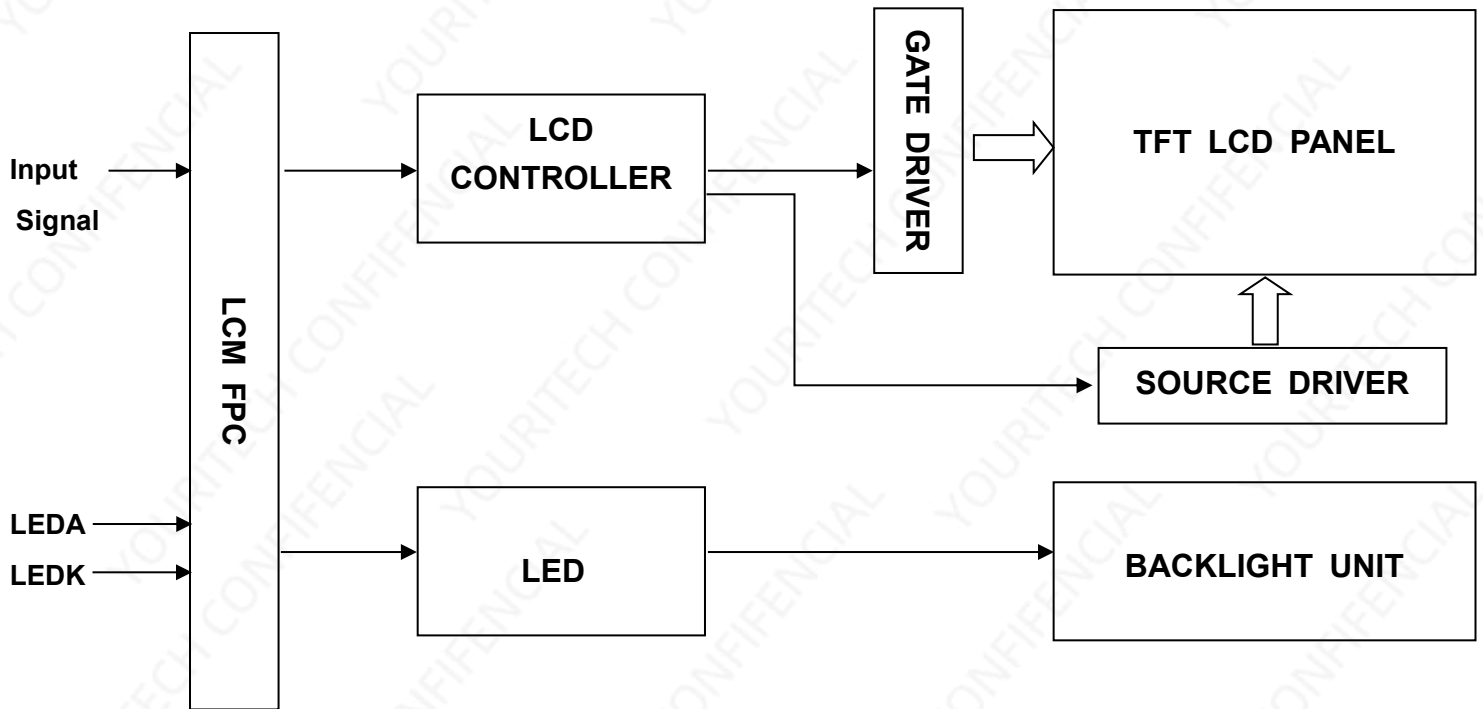
* Features

General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	48.96(H)*48.96(V) (2.73 inch)	mm	
Driver element	TFT active matrix	-	
Display colors	16.7M	colors	
Number of pixels	320(RGB)*320	dots	
Pixel arrangement	RGB vertical stripe	-	
Pixel pitch	0.153(H)*0.153(V)	mm	
Viewing angle	ALL	o'clock	
Controller IC	ST7796U	-	
LCM Interface	1 Lane MIPI	-	
Display mode	Transmissive /Normally Black	-	
Operating temperature	-30 ~ +85	°C	
Storage temperature	-30 ~ +85	°C	

* Mechanical Information

Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)	-	53.4	-	mm	
	Vertical(V)	-	59.9	-	mm	
	Depth(D)	-	2.29	-	mm	
Weight		-	14	-	g	





3. Input terminal Pin Assignment

NO.	SYMBOL	DISCRIPTION	I/O
1	NC		P
2	LEDK	Cathode pin of backlight.	P
3	NC		P
4	LEDA	Anode pin of backlight.	I
5	NC		
6	VCI	Supply Voltage (3.3V).	
7	IOVCC	I/O power supply voltage.	I
8	TE	-Tearing effect output Leave the pin to open when not in use.	I
9	RESET	- The external reset input. Initializes the chip with a low input. Be sure to execute a power-on reset after supplying power.	I
10	GND	Ground.	I
11	MIPI_D1P	MIPI DSI differential data pair (DSI-Dn+/-). If MIPI are not used, they should be connected to DGND	I
12	MIPI_D1N		I/O
13	GND	Ground.	O
14	MIPI_CLP	MIPI DSI differential clock pair (DSI-CLK+/-). If MIPI are not used, they should be connected to DGND.	I
15	MIPI_CLN		I
16	GND	Ground.	I
17	MIPI_D0P	MIPI DSI differential data pair (DSI-Dn+/-). If MIPI are not used, they should be connected to DGND	I
18	MIPI_D0N		I
19	GND	Ground.	O
20	GND	Ground.	A/D



4. LCD Optical Characteristics

4.1 Optical specification

Item		Symbol	Condition	Min.	Typ.	Max.	Unit.	Note
Contrast Ratio		CR	Θ=0 Normal viewing angle	1000	1200	--		(1)(2)
Response time	Rising	T _R +T _F		--	30	35	msec	(1)(3)
	Falling							
Color Gamut		S(%)		--	62	--	%	
Color Filter Chromaticity	White	W _X		0.2985	0.2993	0.3027		(1)(4) CA- 310
		W _Y		0.3381	0.3374	0.3439		
	Red	R _X		0.6398	0.6407	0.6398		
		R _Y		0.3529	0.3525	0.3528		
	Green	G _X		0.3214	0.3220	0.3230		
		G _Y		0.5803	0.5801	0.5799		
	Blue	B _X		0.1434	0.1430	0.1427		
		B _Y		0.0881	0.0872	0.0907		
Viewing angle	Hor.	Θ _L	CR>10	80	85	--		(1)(4)
		Θ _R		80	85	--		
	Ver.	Θ _U		80	85	--		
		Θ _D		80	85	--		
Option View Direction		ALL						

*The data comes from the LCD specification.

Measuring Condition

Measuring surrounding : dark room

Ambient temperature : $25\pm 2^\circ\text{C}$

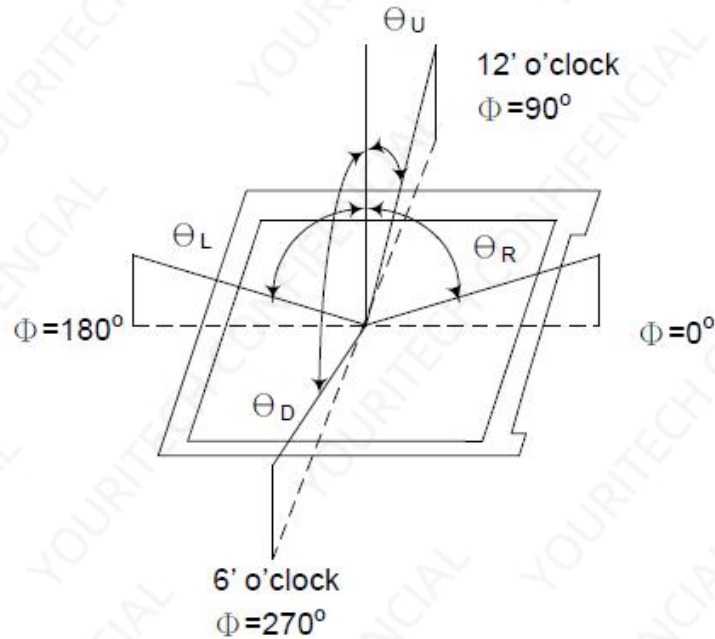
15min. warm-up time.

Measuring Equipment

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.



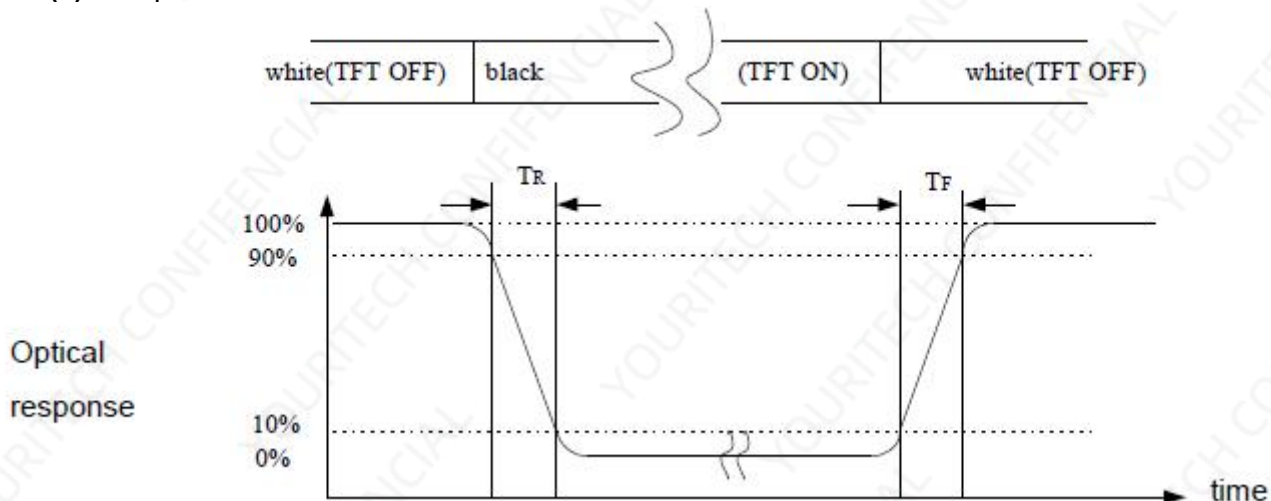
Note (1): Definition of Viewing Angle :



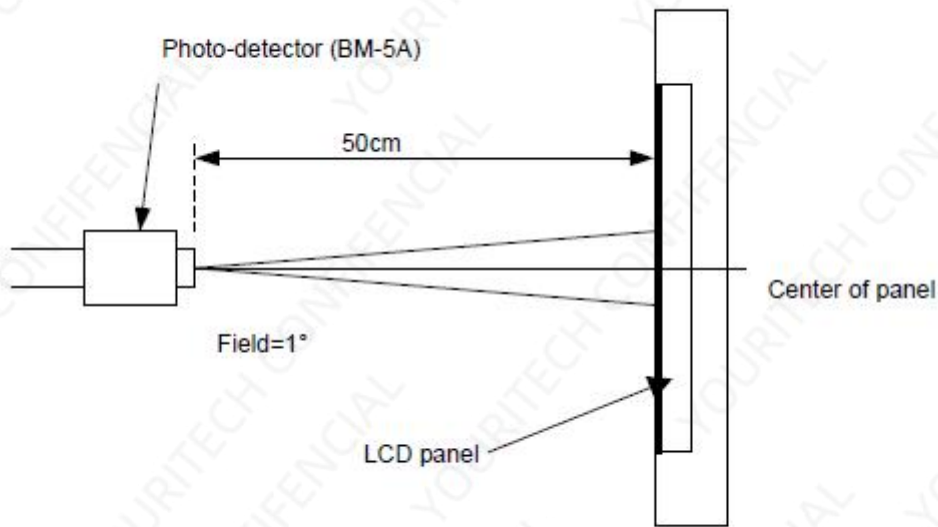
Note (2): Definition of Contrast Ratio(CR) :measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note (3): Response Time



Note (4): Definition of optical measurement setup



5. Electrical Characteristics

5.1 Absolute Maximum Rating

Characteristics	Symbol	Min.	Max.	Unit	Note
Digital Supply Voltage	V _{CI}	-0.3	+4.6	V	Note1
Digital interface supply Voltage	IOVCC	-0.3	+4.6	V	Note1
Operating temperature	T _{OP}	-30	+85	°C	
Storage temperature	T _{ST}	-30	+85	°C	

NOTE1: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	V _{CI}	2.5	3.3	3.6	V	
Digital interface supply Voltage	IOVCC	1.65	1.8	3.3	V	
Normal mode Current consumption	I _{DD}	--	13	--	mA	
Level input voltage	V _{IH}	0.7*IOVCC		IOVCC	V	
	V _{IL}	GND		0.3*IOVCC	V	
Level output voltage	V _{OH}	0.8*IOVCC		IOVCC	V	
	V _{OL}	GND		0.2*IOVCC	V	



5.3 LED Backlight Characteristics

The back-light system is edge-lighting type with 6 chips LED

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I_F	--	20	--	mA	
Forward Voltage	V_F	16.8	19.2	20.4	V	
LCM Luminance	L_v	800	900	--	cd/m ²	Note3
LED life time	Hr	50000	--	--	Hour	Note1,2
Uniformity	Avg	80	--	--	%	Note3

Note1: LED life time (Hr) can be defined as the time in which it continues to operate under the condition:

$T_a=25\pm3\text{ }^{\circ}\text{C}$, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The “LED life time” is defined as the module brightness decrease to 50% original brightness at

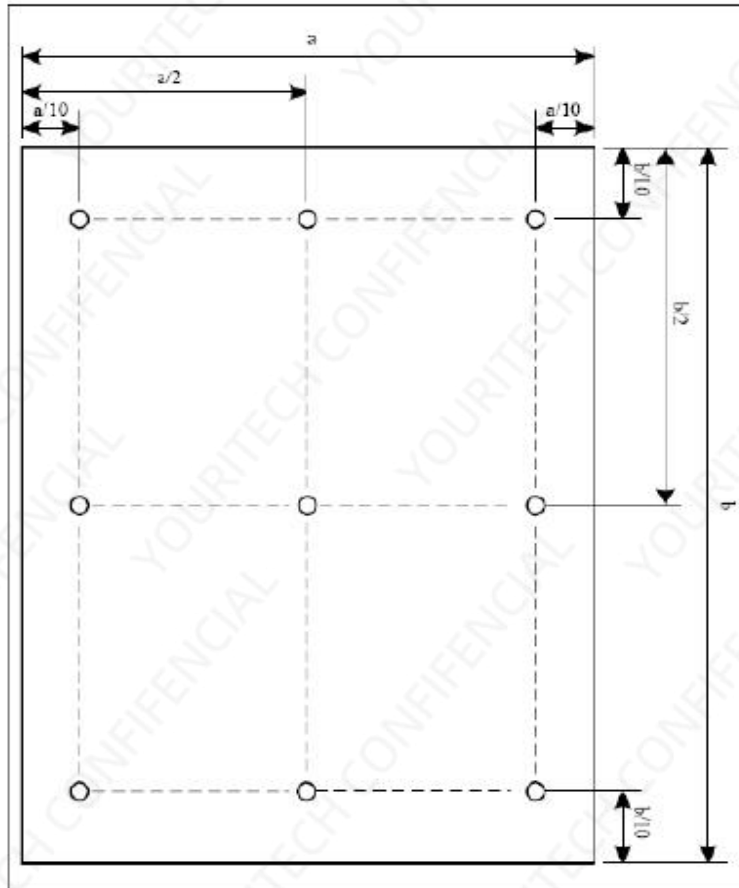
$T_a=25^{\circ}\text{C}$ and $IL=20\text{mA}$. The LED lifetime could be decreased if operating IL is larger than 20mA. The constant current driving method is suggested.



B/L Circuit



Note (3) Luminance Uniformity of these 9 points is defined as below:



$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points (1-9)}}{\text{maximum luminance in 9 points (1-9)}}$$

$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$



6. MIPI Interface Characteristics

6.1 High Speed Mode – Clock Channel Timing

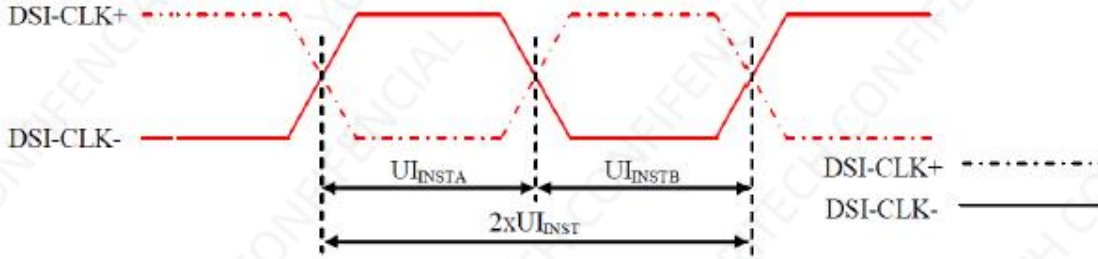


Figure 114 DSI Clock Channel Timing

Table 45 DSI Clock Channel Timing

Signal	Symbol	Parameter	Min	Max	Unit
DSI-CLK+/-	$2xUI_{INST}$	Double UI instantaneous	4	25	ns
DSI-CLK+/-	UI_{INSTA}, UI_{INSTB}	UI instantaneous Half	2	12.5	ns

Note: $UI = UI_{INSTA} = UI_{INSTB}$

6.2 High Speed Mode – Data Clock Channel Timing

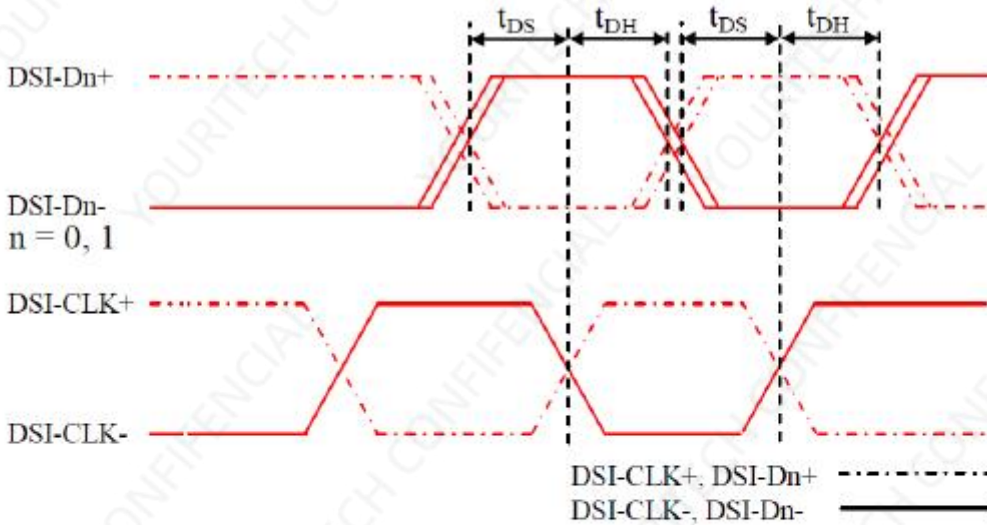


Figure 115 DSI Data to Clock Channel Timings

Table 46 DSI Data to Clock Channel Timings

Signal	Symbol	Parameter	Min	Max
DSI-Dn+/- , n=0 and 1	t_{DS}	Data to Clock Setup time	$0.15xUI$	-
	t_{DH}	Clock to Data Hold Time	$0.15xUI$	-



6.3 High Speed Mode – Rise and Fall Timings

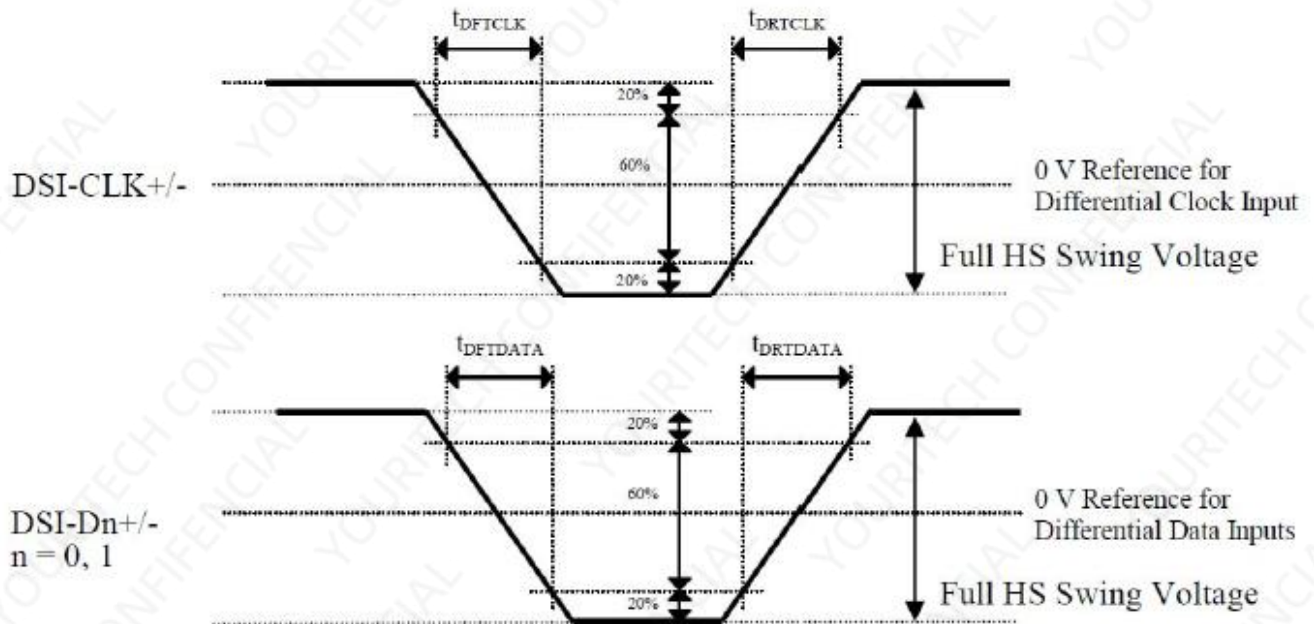


Figure 116 Rise and Fall Timings on Clock and Data Channels

Table 47 Rise and Fall Timings on Clock and Data Channels

Parameter	Symbol	Condition	Specification			Unit
			Min	Typ	Max	
Differential Rise Time for Clock	t_{DRTCLK}	DSI-CLK+/-	-	-	150 (Note)	ps
Differential Rise Time for Data	$t_{DRTDATA}$	DSI-Dn+/- n=0 and 1	-	-	150 (Note)	ps
Differential Fall Time for Clock	t_{DFTCLK}	DSI-CLK+/-	-	-	150 (Note)	ps
Differential Fall Time for Data	$t_{DFTDATA}$	DSI-Dn+/- n=0 and 1	-	-	150 (Note)	ps

Note: The display module has to meet timing requirements, what are defined for the transmitter (MPU) on MIPI D-Phy standard



6.4 Low Speed Mode – Bus Turn Around

Lower Power Mode and its State Periods are illustrated for reference purposes on the Bus Turnaround (BTA) from the MPU to the Display Module (ILI9806E) sequence below.

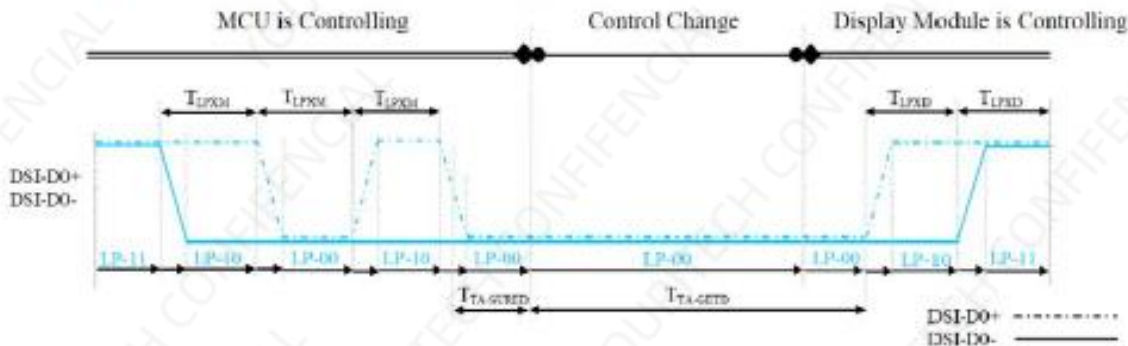


Figure 117 BTA from the MPU to the Display Module

Lower Power Mode and its State Periods are illustrated for reference purposes on the Bus Turnaround (BTA) from the Display Module (ILI9806E) to the MPU sequence below.

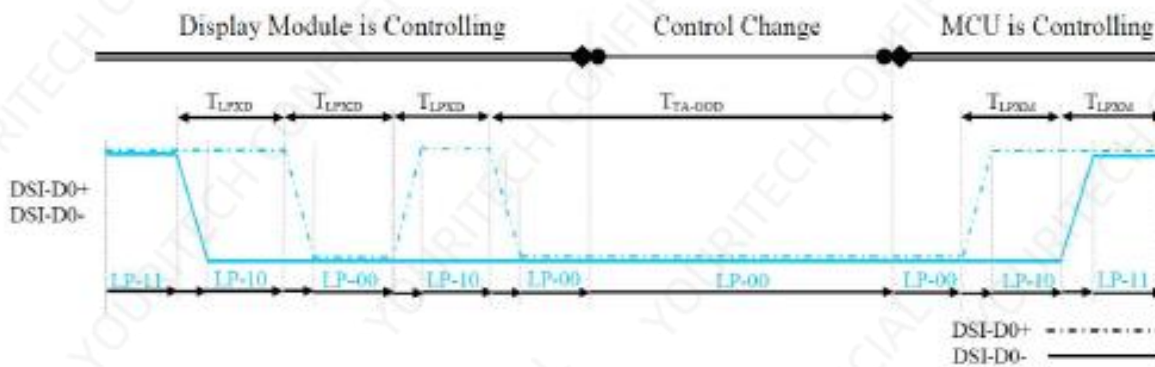


Figure 118 BTA from the Display Module to the MPU

Table 48 Low Power State Period Timings – A

Signal	Symbol	Description	Min	Max	Unit
DSI-D0+/-	T_{LPXM}	Length of LP-00, LP-01, LP-10 or LP-11 periods MPU → Display Module (ILI9806E)	50	75	ns
DSI-D0+/-	T_{LPXD}	Length of LP-00, LP-01, LP-10 or LP-11 periods Display Module (ILI9806E) → MPU	50	75	ns
DSI-D0+/-	$T_{TA-GETD}$	Time-out before the Display Module (ILI9806E) starts driving	T_{LPXD}	$2 \times T_{LPXD}$	ns

Table 49 Low Power State Period Timings – B

Signal	Symbol	Description	Time	Unit
DSI-D0+/-	$T_{TA-GETD}$	Time to drive LP-00 by Display Module (ILI9806E)	$5 \times T_{LPXD}$	ns
DSI-D0+/-	$T_{TA-GETD}$	Time to drive LP-00 after turnaround request – MPU	$4 \times T_{LPXD}$	ns



6.5 Data Lanes from Low Power Mode to High Speed Mode

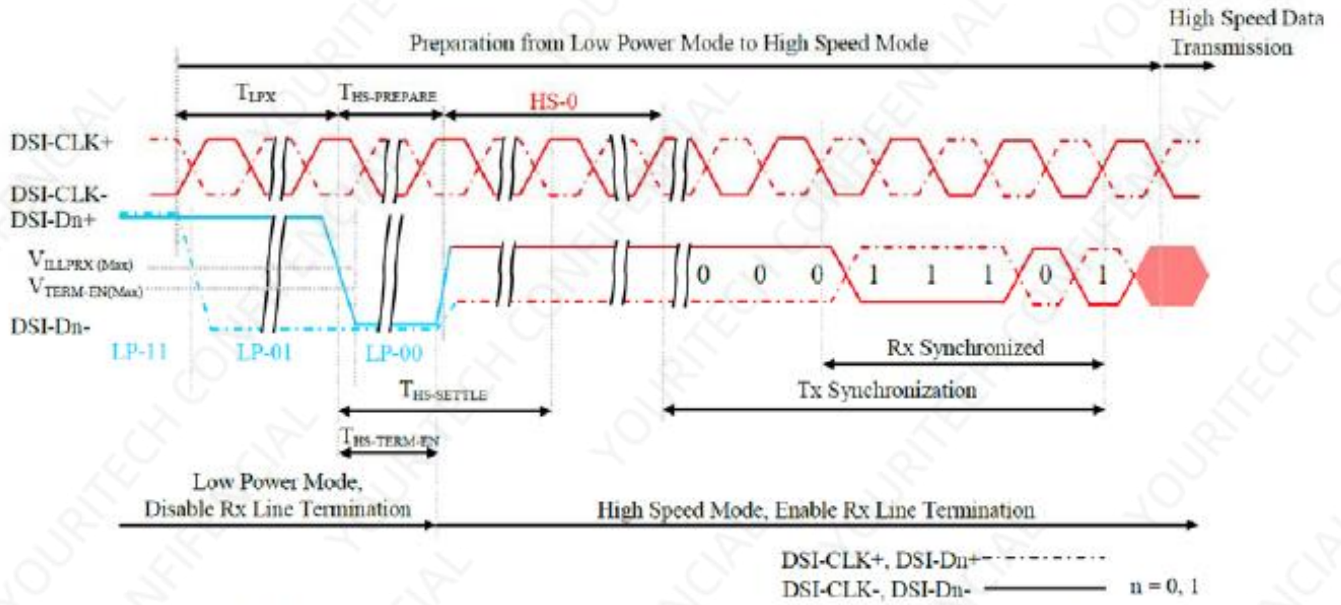


Figure 119 Data Lanes – Low Power Mode to High Speed Mode Timings

Table 50 Data Lanes – Low Power Mode to High Speed Mode Timings

Signal	Symbol	Description	Min	Max	Unit
DSI-Dn+/-, n=0 and 1	T_{LPX}	Length of any Low Power State Period	50	-	ns
DSI-Dn+/-, n=0 and 1	$T_{HS-PREPARE}$	Time to drive LP-00 to prepare for HS Transmission	$40+4xUI$	$85+6xUI$	ns
DSI-Dn+/-, n=0 and 1	$T_{HS-TERM-EN}$	Time to enable Data Lane Receiver line termination measured from when Dn crosses V_{ILMAX}	-	$35+4xUI$	ns



6.6 Data Lanes from Low Power Mode to High Speed Mode

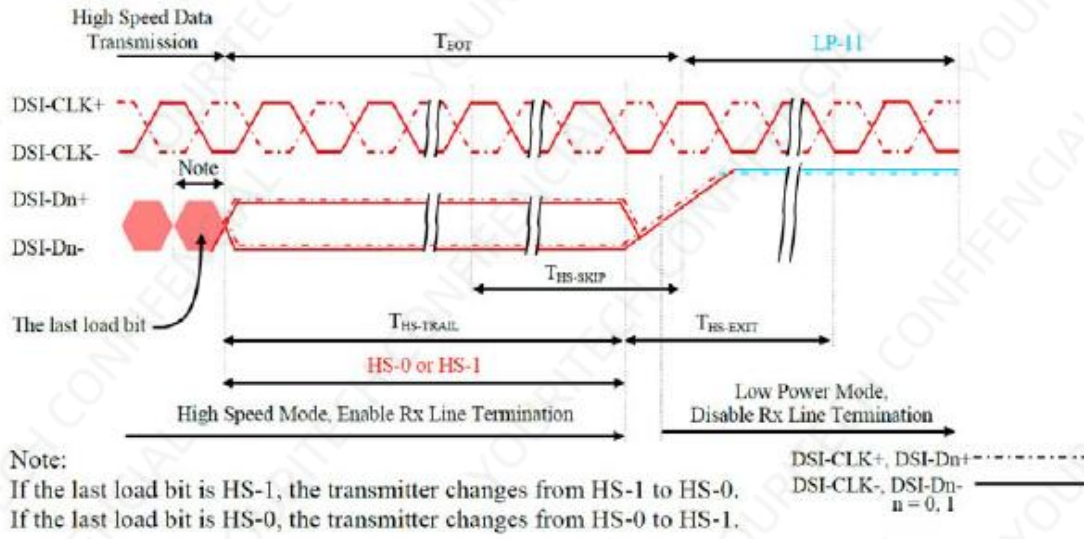


Figure 120 Data Lanes – High Speed Mode to Low Power Mode Timings

Table 51 Data Lanes – High Speed Mode to Low Power Mode Timings

Signal	Symbol	Description	Min	Max	Unit
DSI-Dn+/-, n=0 and 1	$T_{HS-SKIP}$	Time-Out at Display Module (ILI9806E) to ignore transition period of EoT	40	$55+4 \times UI$	ns
DSI-Dn+/-, n=0 and 1	$T_{HS-EXIT}$	Time to driver LP-11 after HS burst	100	-	ns



6.7 DSI Clock Burst – High Speed Mode to/from Low Power Mode

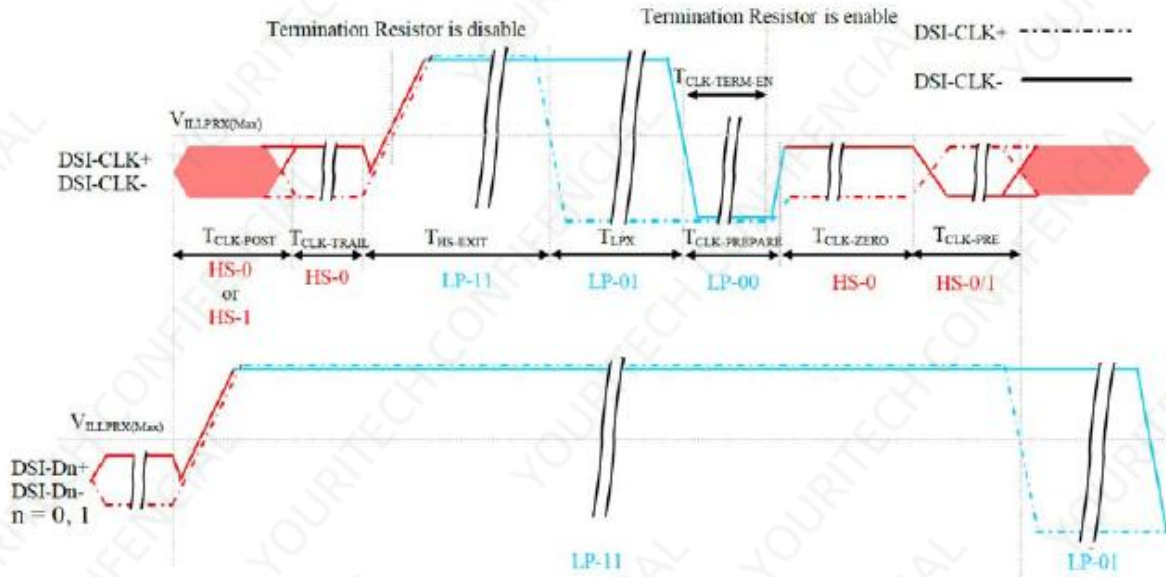


Figure 121 Clock Lanes – High Speed Mode to/from Low Power Mode Timings

Table 52 Clock Lanes – High Speed Mode to/from Low Power Mode Timings

Signal	Symbol	Description	Min	Max	Unit
DSI-CLK+/-	$T_{CLK-POST}$	Time that the MPU shall continue sending HS clock after the last associated Data Lanes has transitioned to LP mode	$60+52 \times UI$	-	ns
DSI-CLK+/-	$T_{CLK-TRAIL}$	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	ns
DSI-CLK+/-	$T_{HS-EXIT}$	Time to drive LP-11 after HS burst	100	-	ns
DSI-CLK+/-	$T_{CLK-PREPARE}$	Time to drive LP-00 to prepare for HS transmission	38	95	ns
DSI-CLK+/-	$T_{CLK-TERM-EN}$	Time-out at Clock Lane to enable HS termination	-	38	ns
DSI-CLK+/-	$T_{CLK-PREPARE}$	Minimum lead HS-0 drive period before starting Clock	300	-	ns
DSI-CLK+/-	$T_{CLK-PRE}$	Time that the HS clock shall be driven prior to any associated Data Lane beginning the transition from LP to HS mode	$8 \times UI$	-	ns



6.8 Reset input timing

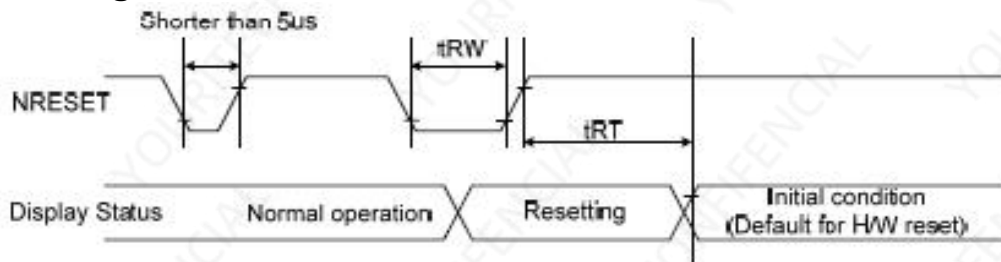


Figure 102 Reset Timing

Table 41 Reset Timing

Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		us
	tRT	Reset cancel		5(note 1,5)	ms
				120 (note 1,6,7)	ms

Note:

1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from OTP to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the Table 43.

Table 42 Reset Descript

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out mode. The display remains the blank state in Sleep In mode.) and then return to Default condition for Hardware Reset.
4. Spike Rejection also applies during a valid reset pulse as shown below:

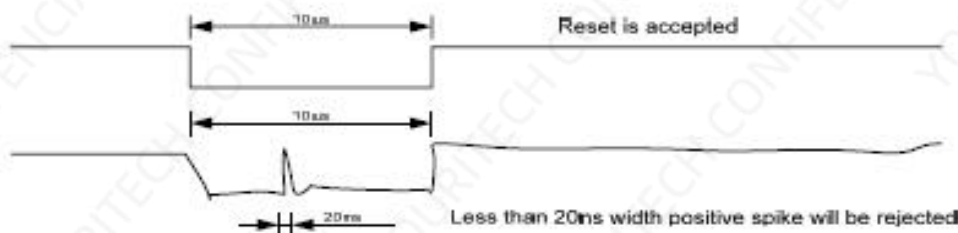


Figure 103 Positive Noise Pulse during Reset Low

5. When Reset applied during Sleep In Mode.
6. When Reset applied during Sleep Out Mode.
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.



7. LCD Module Out-Going Quality Level

7.1 VISUAL & FUNCTION INSPECTION STANDARD

7.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

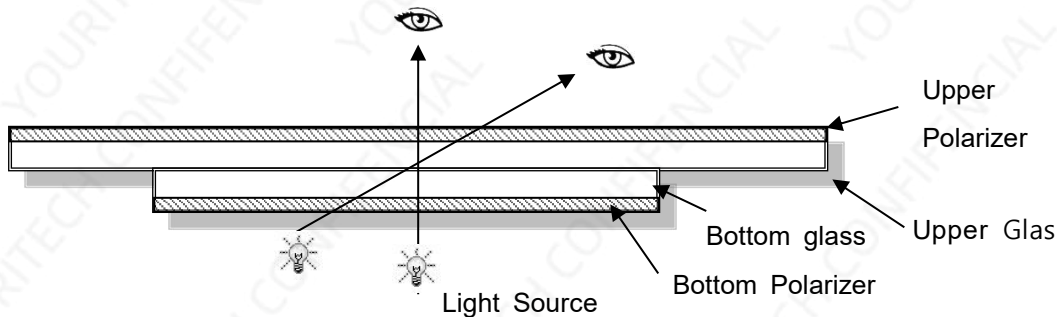
Temperature : $25\pm 5^{\circ}\text{C}$

Humidity : $65\%\pm 10\%\text{RH}$

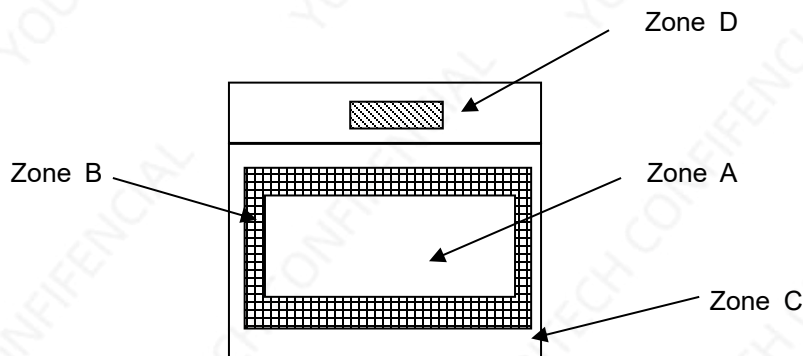
Viewing Angle : Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



7.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer

Zone D : IC Bonding Area

Note:As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer



7.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class II

AQL:

Major defect	Minor defect
0.65	1.5

LCD: Liquid Crystal Display , LCM: Liquid Crystal Module,

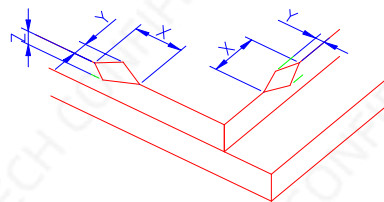
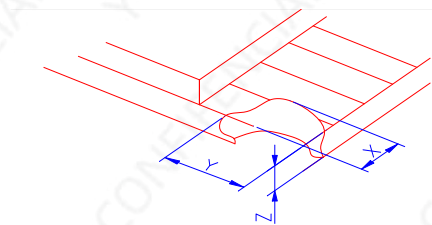
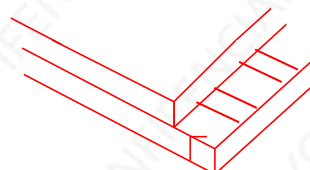
No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. etc...	Major
2	Missing	Missing components and etc...	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed, deformation and etc...	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Spot/Line defect	Light dot, Dim spot, (Note1) Polarizer Air Bubble, Polarizer accidented spot and etc.	
6	Soldering appearance	Good soldering , Peeling off is not allowed and etc.	
7	LCD/Polarizer	Black/White spot/line, scratch, crack, etc.	

Note1: a) Light dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.

b) Dim dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture.



7.1.4 Criteria (Visual)

Number	Items	Criteria(mm)						
1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height L: Length of IT O, T: Height of LCD	(1) The edge of LCD broken	 <table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr></table>	X	Y	Z	≤3.0mm	<Inner border line of the seal	≤T
X	Y	Z						
≤3.0mm	<Inner border line of the seal	≤T						
	(2)LCD corner broken	 <table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr></table>	X	Y	Z	≤3.0mm	≤L	≤T
X	Y	Z						
≤3.0mm	≤L	≤T						
	(3) LCD crack	 Crack Not allowed						



Spot defect

$\Phi=(X+Y)/2$

① light dot (black/white spot , pinhole, stain, etc.)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.15$	Ignore	Ignore	
$0.15 < \Phi \leq 0.25$	3(distance $\geq 10\text{mm}$)		
$0.25 < \Phi \leq 0.4$	2(distance $\geq 10\text{mm}$)		
$\Phi > 0.4$	0		

② Dim spot (light leakage、dent、dark spot, etc)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.15$	Ignore	Ignore	
$0.15 < \Phi \leq 0.25$	3(distance $\geq 10\text{mm}$)		
$0.25 < \Phi \leq 0.4$	2(distance $\geq 10\text{mm}$)		
$\Phi > 0.4$	0		

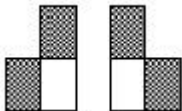
③ Polarizer accidented spot

Zone Size (mm)	Acceptable Qty			
	A	B	C	
$\Phi \leq 0.2$	Ignore		Ignore	
$0.2 < \Phi \leq 0.5$	2(distance $\geq 10\text{mm}$)			
$\Phi > 0.5$	0			

④Polarizer Bubble

Zone Size (mm)	Acceptable Qty			
	A	B	C	
$\Phi \leq 0.2$	Ignore		Ignore	
$0.2 < \Phi \leq 0.4$	3(distance $\geq 10\text{mm}$)			
$\Phi > 0.4$	0			



3.0	LCD Pixel defect	Pixel bad points																							
		<table> <tr> <th>Item</th><th>Zone A</th><th>Acceptable Qt</th></tr> <tr> <td rowspan="3">Bright dot</td><td>Random</td><td>$N \leq 2$</td></tr> <tr> <td>2 dots adjacent</td><td>$N \leq 0$</td></tr> <tr> <td>3 dots adjacent</td><td>$N \leq 0$</td></tr> <tr> <td rowspan="3">Dark dot</td><td>Random</td><td>$N \leq 2$</td></tr> <tr> <td>2 dots adjacent</td><td>$N \leq 0$</td></tr> <tr> <td>3 dots adjacent</td><td>$N \leq 0$</td></tr> <tr> <td>Distance</td><td> 1. Minimum Distance Between Bright dots. 2. Minimum Distance Between dark dots 3. Minimum Distance Between dark and bright dot. </td><td>5mm</td></tr> <tr> <td colspan="2">Total bright and dark dot</td><td>$N \leq 4$</td></tr> </table> Note: A) Bright dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern. B) Dark dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture. C) 2 dot adjacent = 1 pair = 2 dots Picture:     2 dot adjacent 2 dot adjacent (vertical) 2 dot adjacent (slant)	Item	Zone A	Acceptable Qt	Bright dot	Random	$N \leq 2$	2 dots adjacent	$N \leq 0$	3 dots adjacent	$N \leq 0$	Dark dot	Random	$N \leq 2$	2 dots adjacent	$N \leq 0$	3 dots adjacent	$N \leq 0$	Distance	1. Minimum Distance Between Bright dots. 2. Minimum Distance Between dark dots 3. Minimum Distance Between dark and bright dot.	5mm	Total bright and dark dot		$N \leq 4$
Item	Zone A	Acceptable Qt																							
Bright dot	Random	$N \leq 2$																							
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Distance	1. Minimum Distance Between Bright dots. 2. Minimum Distance Between dark dots 3. Minimum Distance Between dark and bright dot.	5mm																							
Total bright and dark dot		$N \leq 4$																							



4.0	Line defect (LCD /Polarizer backlight black/white line, scratch, stain)	 W: width, L : length N : Count	Width(mm)	Length(m) m)	Acceptable Qty		
	A				B	C	
	$\Phi \leq 0.05$		Ignore	Ignore		Ignore	
	$0.05 < W \leq 0.06$		$L \leq 4.0$	$N \leq 3$			
	$0.06 < W \leq 0.08$		$L \leq 3.0$	$N \leq 2$			
	$W > 0.08$		Define as spot defect				
5.0	Electronic Components SMT.	Not allow missing parts, solderless connection, cold solder joint, mismatch, The positive and negative polarity opposite					
6.0	Display color& Brightness.	1. Color: Measuring the color coordinates, The measurement standard according to the datasheet or samples. 2. Brightness: Measuring the brightness of White screen, The measurement standard according to the datasheet or Samples.					
7.0	LCD Mura/Waving/ Hot spot	Not visible through 5% ND filter in 50% gray or judge by limit sample if necessary.					

Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed



8. Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	85°C,96H	Inspection after 2~4hours storage at room temperature, the sample shall be free from defects: 1.Air bubble in the LCD; 2.Non-display; 3.Missing segments/line; 4.Glass crack; 5.Current IDD is twice higher than initial value.
Low Temperature Operating	-30°C, 96HR	
High Temperature Storage	85°C, 96HR	
Low Temperature Storage	-30°C, 96HR	
High Temperature & High Humidity Operating	+60°C, 90% RH ,96 hours.	
Thermal Shock (Non-operation)	-30°C,30 min ↔85°C,30 min, Change time:5min 20CYC.	
ESD test	C=150pF, R=330,5points/panel Air:±8KV, 5times; Contact:±6KV, 5 times; (Environment: 15°C~35°C, 30%~60%).	
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	
Box Drop Test	1 Corner 3 Edges 6 faces,80cm (MEDIUM BOX)	

Remark:

- 1.The test samples should be applied to only one test item.
- 2.Sample size for each test item is 5~10pcs.
- 3.For Damp Proof Test, Pure water(Resistance > 10MΩ) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.
6. The color fading mura of polarizing filter should not care.



9. Cautions and Handling Precautions

9.1 Handling and Operating the Module

- (1) When the module is assembled, it should be attached to the system firmly.
Do not warp or twist the module during assembly work.
- (2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- (4) Do not allow drops of water or chemicals to remain on the display surface.
If you have the droplets for a long time, staining and discoloration may occur.
- (5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- (6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.
Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static; it may cause damage to the CMOS ICs.
- (9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (10) Do not disassemble the module.
- (11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (12) Pins of I/F connector shall not be touched directly with bare hands.
- (13) Do not connect, disconnect the module in the "Power ON" condition.
- (14) Power supply should always be turned on/off by the item 6.1 Power On Sequence & 6.2 Power Off Sequence

9.2 Storage and Transportation.

- (1) Do not leave the panel in high temperature, and high humidity for a long time.
It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- (2) Do not store the TFT-LCD module in direct sunlight.
- (3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- (4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- (5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.



10. Packing

---TBD-----

